

## P-Channel 60-V (D-S) MOSFET

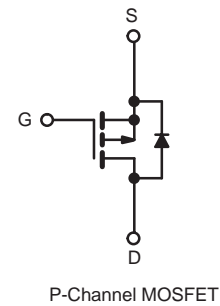
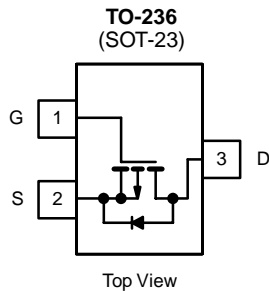
| PRODUCT SUMMARY           |                  |      |
|---------------------------|------------------|------|
| $V_{DS}$ (V)              | - 60             |      |
| $R_{DS(on)}$ ( $\Omega$ ) | $V_{GS} = -10$ V | 0.04 |
| $Q_g$ (Max.) (nC)         | 12               |      |
| $Q_{gs}$ (nC)             | 3.8              |      |
| $Q_{gd}$ (nC)             | 5.1              |      |
| Configuration             | Single           |      |

### FEATURES

- Isolated Package
- High Voltage Isolation = 2.5 kV<sub>RMS</sub> (t = 60 s; f = 60 Hz)
- Sink to Lead Creepage Distance = 4.8 mm
- P-Channel
- 175 °C Operating Temperature
- Dynamic dV/dt Rating
- Low Thermal Resistance
- Lead (Pb)-free Available



Available  
**RoHS\***  
 COMPLIANT


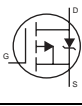


| ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted |                    |                |                  |          |
|--|--------------------|----------------|------------------|----------|
| PARAMETER  | SYMBOL             | LIMIT          | UNIT             |          |
| Drain-Source Voltage   | $V_{DS}$           | - 60           | V                |          |
| Gate-Source Voltage  | $V_{GS}$           | $\pm 20$       |                  |          |
| Continuous Drain Current                                       | $V_{GS}$ at - 10 V | $T_C = 25$ °C  | - 5.2            | A        |
|  |                    | $T_C = 100$ °C | - 3.8            |          |
| Pulsed Drain Current <sup>a</sup>                              | $I_{DM}$           | - 21           |                  |          |
| Linear Derating Factor   |                    | 0.18           | W/°C             |          |
| Single Pulse Avalanche Energy <sup>b</sup>                     | $E_{AS}$           | 120            | mJ               |          |
| Repetitive Avalanche Current <sup>a</sup>                      | $I_{AR}$           | - 5.2          | A                |          |
| Repetitive Avalanche Energy <sup>a</sup>                       | $E_{AR}$           | 2.7            | mJ               |          |
| Maximum Power Dissipation                                      | $T_C = 25$ °C      | $P_D$          | 27               | W        |
| Peak Diode Recovery dV/dt <sup>c</sup>                         |                    | dV/dt          | - 4.5            | V/ns     |
| Operating Junction and Storage Temperature Range               |                    | $T_J, T_{stg}$ | - 55 to + 175    | °C       |
| Soldering Recommendations (Peak Temperature)                   | for 10 s           |                | 300 <sup>d</sup> |          |
| Mounting Torque  | 6-32 or M3 screw   |                | 10               | lbf · in |
|  |                    |                | 1.1              | N · m    |

### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = -25$  V, starting  $T_J = 25$  °C, L = 5.0 mH,  $R_G = 25$   $\Omega$ ,  $I_{AS} = -5.3$  A (see fig. 12).
- $I_{SD} \leq -6.7$  A,  $dI/dt \leq 90$  A/ $\mu$ s,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 175$  °C.
- 1.6 mm from case.

| THERMAL RESISTANCE RATINGS       |            |      |      |      |
|----------------------------------|------------|------|------|------|
| PARAMETER                        | SYMBOL     | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient      | $R_{thJA}$ | -    | 65   | °C/W |
| Maximum Junction-to-Case (Drain) | $R_{thJC}$ | -    | 5.5  |      |

| SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted |                     |  |      |        |           |               |
|--|---------------------|--|------|--------|-----------|---------------|
| PARAMETER  | SYMBOL              | TEST CONDITIONS  | MIN. | TYP.   | MAX.      | UNIT          |
| <b>Static</b>  |                     |  |      |        |           |               |
| Drain-Source Breakdown Voltage   | $V_{DS}$            | $V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$   | -60  | -      | -         | V             |
| $V_{DS}$ Temperature Coefficient   | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}$ , $I_D = -1\text{ mA}$   | -    | -0.060 | -         | V/°C          |
| Gate-Source Threshold Voltage  | $V_{GS(th)}$        | $V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$   | -1.0 | -      | -2.5      | V             |
| Gate-Source Leakage  | $I_{GSS}$           | $V_{GS} = \pm 20\text{ V}$   | -    | -      | $\pm 100$ | nA            |
| Zero Gate Voltage Drain Current  | $I_{DSS}$           | $V_{DS} = -60\text{ V}, V_{GS} = 0\text{ V}$   | -    | -      | -100      | $\mu\text{A}$ |
|  |                     | $V_{DS} = -48\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$  | -    | -      | -500      |               |
| Drain-Source On-State Resistance   | $R_{DS(on)}$        | $V_{GS} = -10\text{ V}, I_D = -3.2\text{ A}^b$   | -    | 0.05   | -         | $\Omega$      |
| Forward Transconductance   | $g_{fs}$            | $V_{DS} = -25\text{ V}, I_D = -3.2\text{ A}^b$   | 1.6  | -      | -         | S             |
| <b>Dynamic</b>   |                     |  |      |        |           |               |
| Input Capacitance  | $C_{iss}$           | $V_{GS} = 0\text{ V}, V_{DS} = -25\text{ V}, f = 1.0\text{ MHz}$ , see fig. 5  | -    | 270    | -         | pF            |
| Output Capacitance   | $C_{oss}$           |  | -    | 170    | -         |               |
| Reverse Transfer Capacitance   | $C_{rss}$           |  | -    | 31     | -         |               |
| Drain to Sink Capacitance  | $C$                 | $f = 1.0\text{ MHz}$   | -    | 12     | -         |               |
| Total Gate Charge  | $Q_g$               | $V_{GS} = -10\text{ V}, I_D = -4.7\text{ A}, V_{DS} = -48\text{ V}$ , see fig. 6 and 13 <sup>b</sup>   | -    | -      | 12        | nC            |
| Gate-Source Charge   | $Q_{gs}$            |  | -    | -      | 3.8       |               |
| Gate-Drain Charge  | $Q_{gd}$            |  | -    | -      | 5.1       |               |
| Turn-On Delay Time   | $t_{d(on)}$         | $V_{DD} = -30\text{ V}, I_D = -4.7\text{ A}, R_G = 24\text{ }\Omega, R_D = 4.0\text{ }\Omega$ , see fig. 10 <sup>b</sup>                               | -    | 11     | -         | ns            |
| Rise Time  | $t_r$               |  | -    | 63     | -         |               |
| Turn-Off Delay Time  | $t_{d(off)}$        |  | -    | 9.6    | -         |               |
| Fall Time  | $t_f$               |  | -    | 31     | -         |               |
| Internal Drain Inductance  | $L_D$               | Between lead, 6 mm (0.25") from package and center of die contact  | -    | 4.5    | -         | nH            |
| Internal Source Inductance   | $L_S$               |  | -    | 7.5    | -         |               |
| <b>Drain-Source Body Diode Characteristics</b>                           |                     |  |      |        |           |               |
| Continuous Source-Drain Diode Current                                    | $I_S$               | MOSFET symbol showing the integral reverse p-n junction diode      | -    | -      | -5.2      | A             |
| Pulsed Diode Forward Current <sup>a</sup>                                | $I_{SM}$            |  | -    | -      | -21       |               |
| Body Diode Voltage   | $V_{SD}$            | $T_J = 25\text{ }^\circ\text{C}, I_S = -5.2\text{ A}, V_{GS} = 0\text{ V}^b$   | -    | -      | -5.5      | V             |
| Body Diode Reverse Recovery Time   | $t_{rr}$            | $T_J = 25\text{ }^\circ\text{C}, I_F = -4.7\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$  | -    | 80     | 160       | ns            |
| Body Diode Reverse Recovery Charge                                       | $Q_{rr}$            |  | -    | 0.096  | 0.19      | $\mu\text{C}$ |
| Forward Turn-On Time   | $t_{on}$            | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )  |      |        |           |               |

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).  
 b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

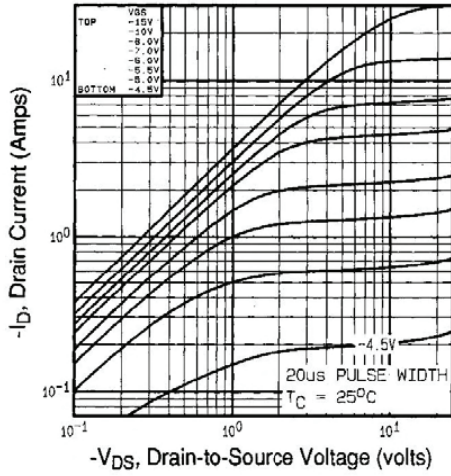


Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^\circ\text{C}$

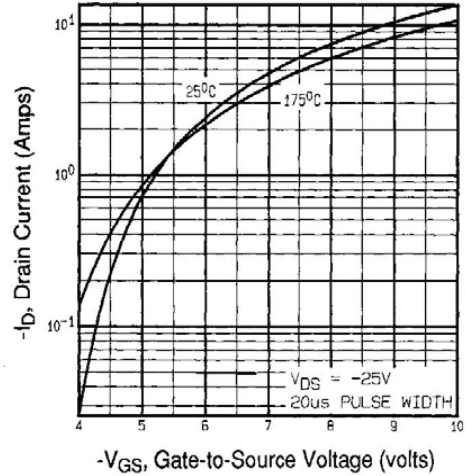


Fig. 3 - Typical Transfer Characteristics

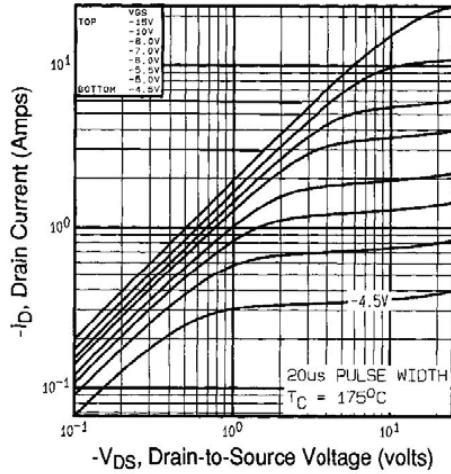


Fig. 2 - Typical Output Characteristics,  $T_C = 175\text{ }^\circ\text{C}$

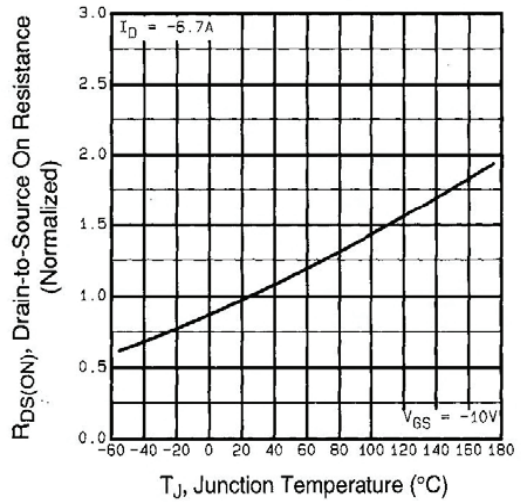


Fig. 4 - Normalized On-Resistance vs. Temperature

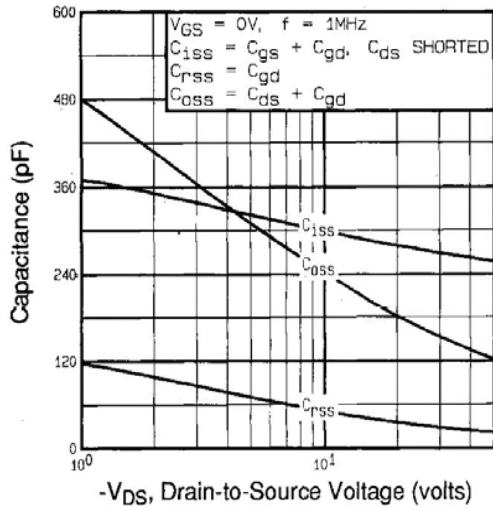


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

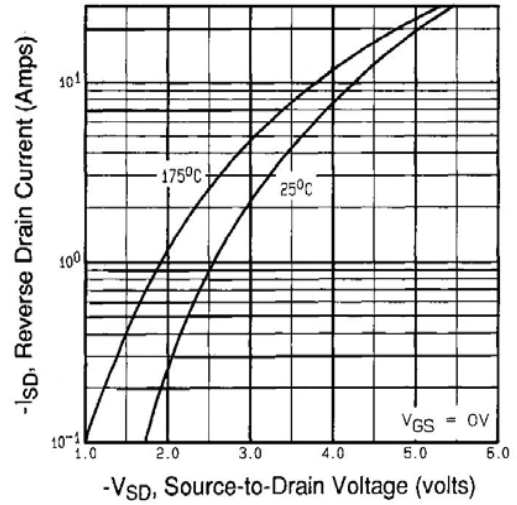


Fig. 7 - Typical Source-Drain Diode Forward Voltage

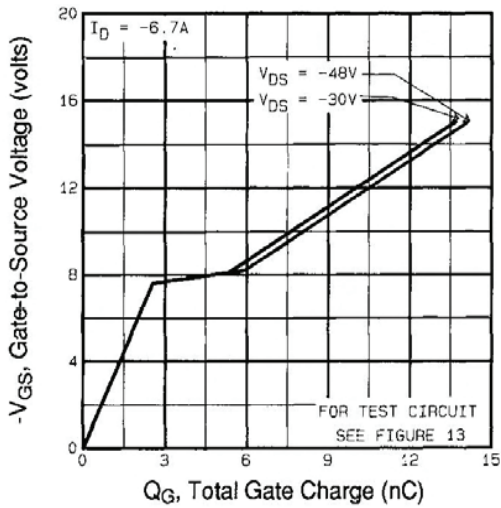


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

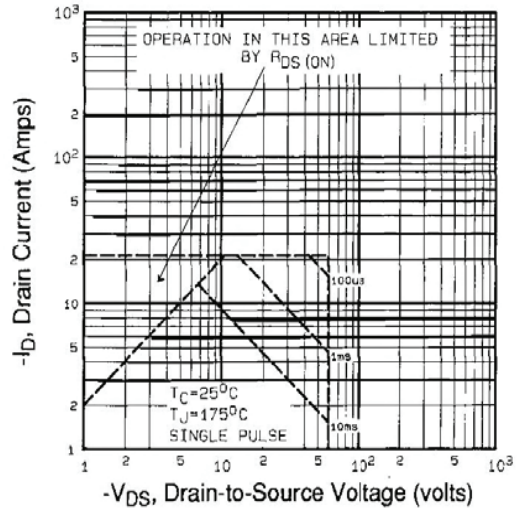


Fig. 8 - Maximum Safe Operating Area

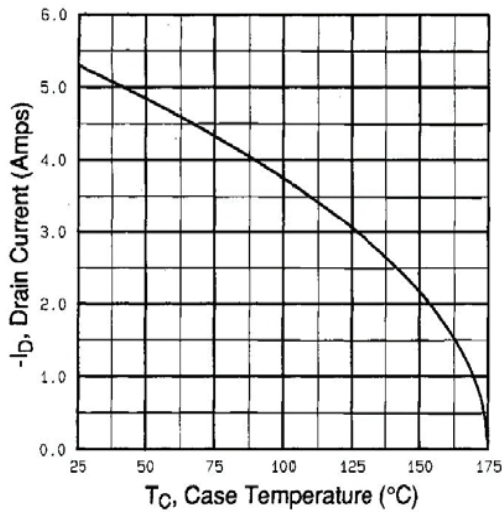


Fig. 9 - Maximum Drain Current vs. Case Temperature

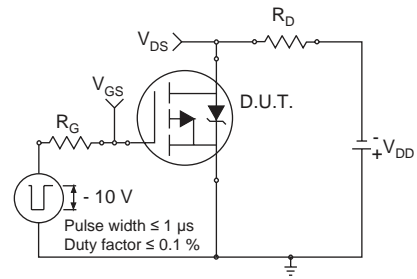


Fig. 10a - Switching Time Test Circuit

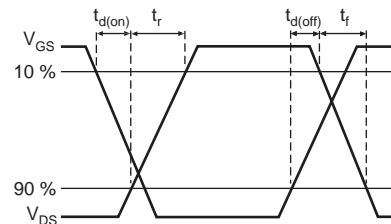


Fig. 10b - Switching Time Waveforms

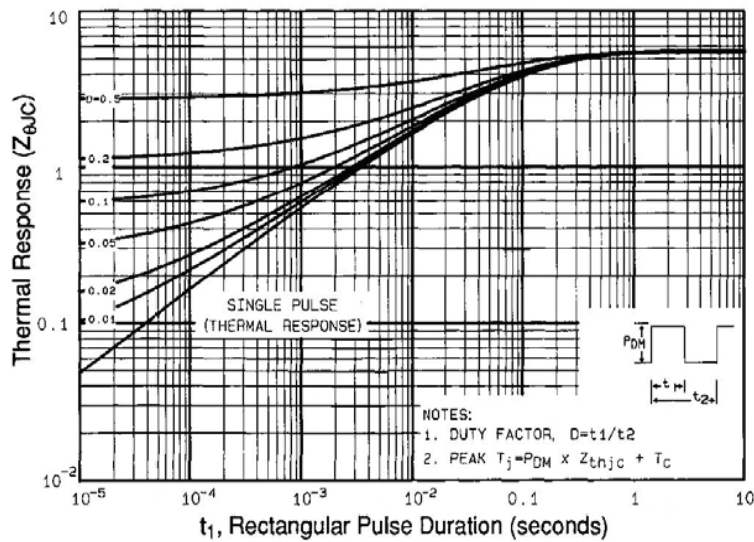


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

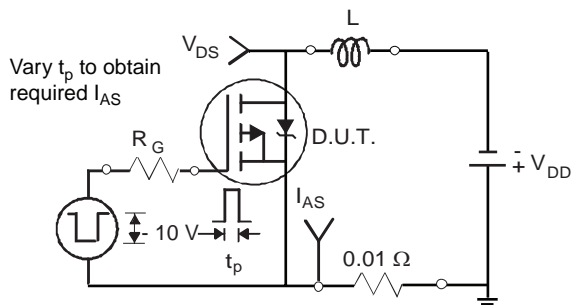


Fig. 12a - Unclamped Inductive Test Circuit

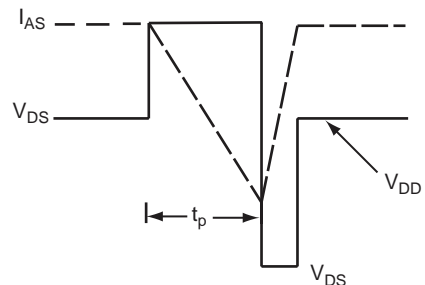


Fig. 12b - Unclamped Inductive Waveforms

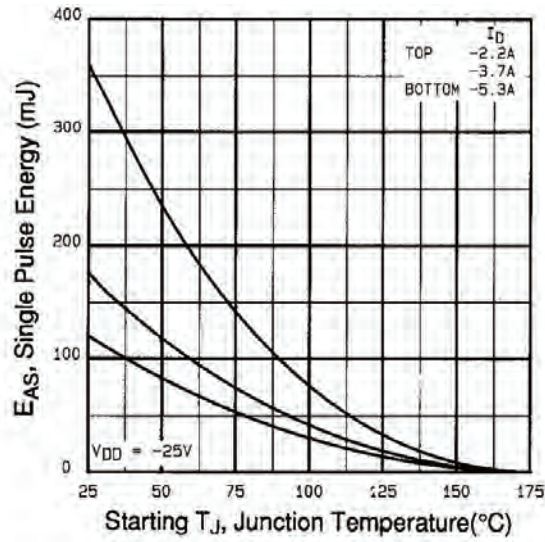


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

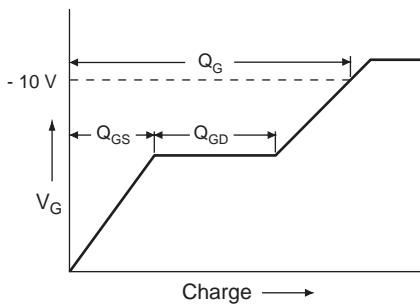


Fig. 13a - Basic Gate Charge Waveform

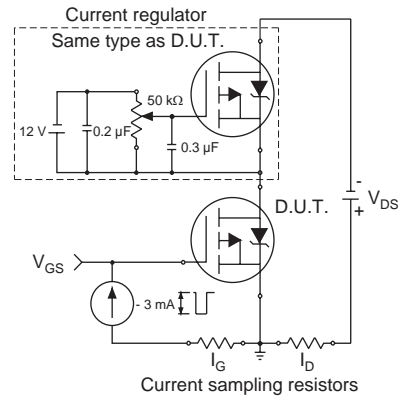
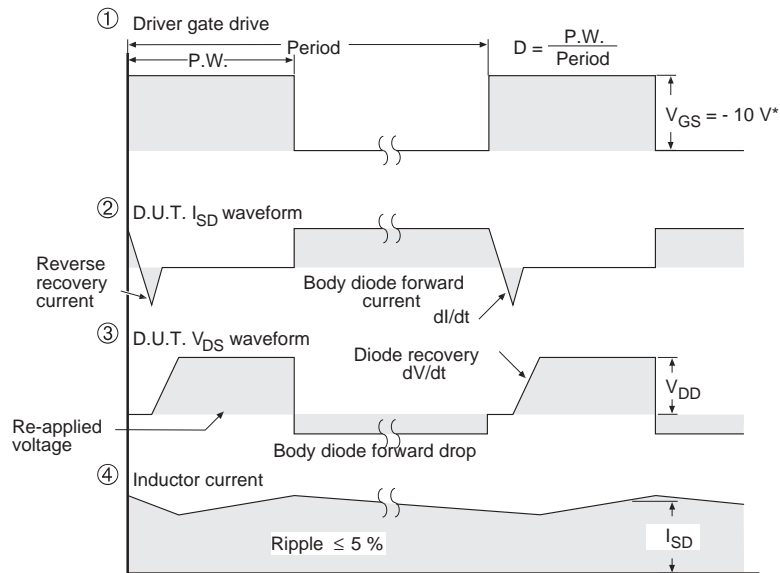
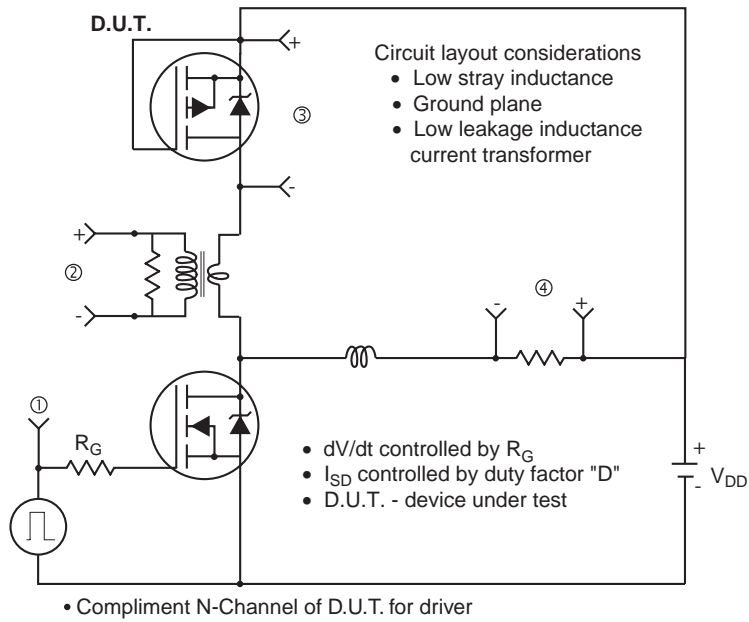


Fig. 13b - Gate Charge Test Circuit

**Peak Diode Recovery dV/dt Test Circuit**

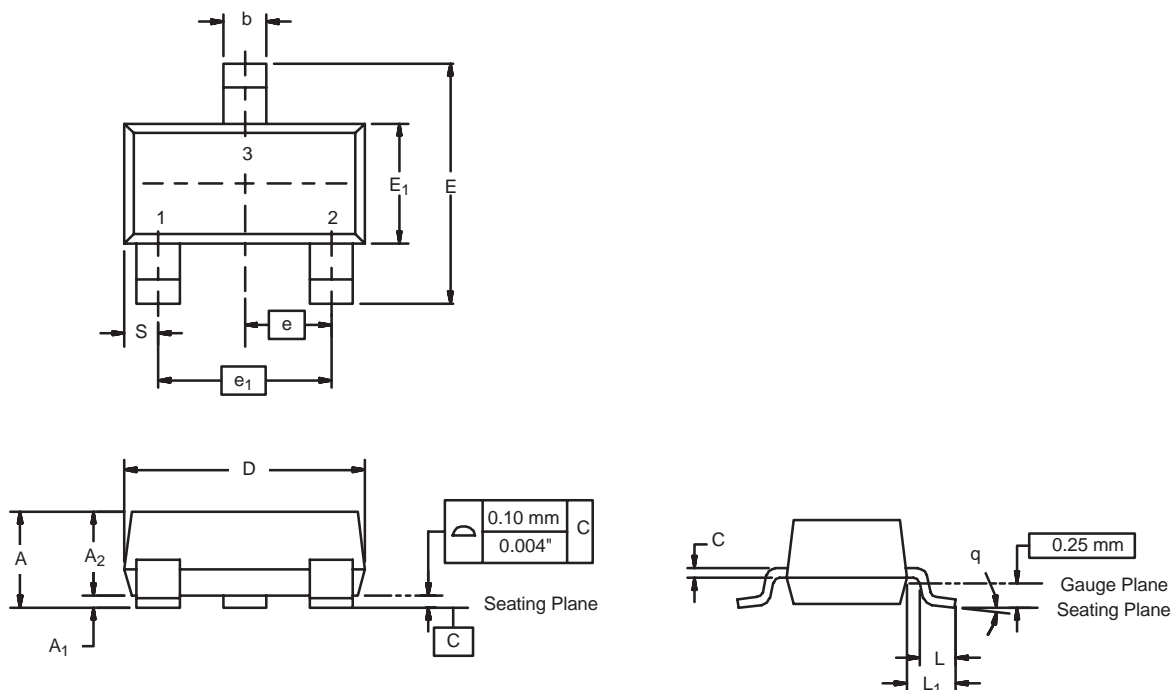


\*  $V_{GS} = -5 V$  for logic level and  $-3 V$  drive devices

**Fig. 14 - For P-Channel**



**SOT-23 (TO-236): 3-LEAD**

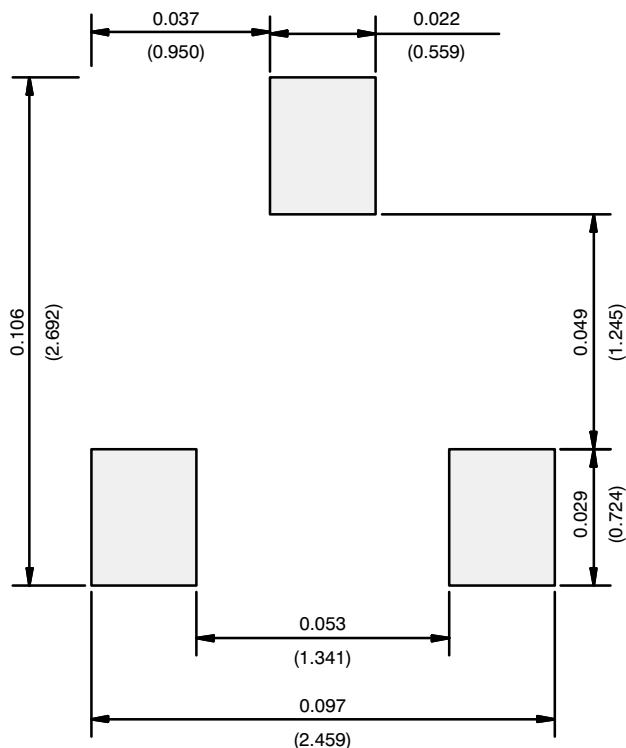


| Dim            | MILLIMETERS |      | INCHES     |       |
|----------------|-------------|------|------------|-------|
|                | Min         | Max  | Min        | Max   |
| A              | 0.89        | 1.12 | 0.035      | 0.044 |
| A <sub>1</sub> | 0.01        | 0.10 | 0.0004     | 0.004 |
| A <sub>2</sub> | 0.88        | 1.02 | 0.0346     | 0.040 |
| b              | 0.35        | 0.50 | 0.014      | 0.020 |
| c              | 0.085       | 0.18 | 0.003      | 0.007 |
| D              | 2.80        | 3.04 | 0.110      | 0.120 |
| E              | 2.10        | 2.64 | 0.083      | 0.104 |
| E <sub>1</sub> | 1.20        | 1.40 | 0.047      | 0.055 |
| e              | 0.95 BSC    |      | 0.0374 Ref |       |
| e <sub>1</sub> | 1.90 BSC    |      | 0.0748 Ref |       |
| L              | 0.40        | 0.60 | 0.016      | 0.024 |
| L <sub>1</sub> | 0.64 Ref    |      | 0.025 Ref  |       |
| S              | 0.50 Ref    |      | 0.020 Ref  |       |
| q              | 3°          | 8°   | 3°         | 8°    |

ECN: S-03946-Rev. K, 09-Jul-01  
DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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